

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|------------------|--------------------------------------|----------------------|--------------|--------------------------------------|-------------------------|
| 5962-9070601MEA | ACTIVE | CDIP | J | 16 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9070601ME A CD54HCT367F3A | Samples |
| CD54HC367F3A | ACTIVE | CDIP | J | 16 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 8500201EA CD54HC367F3A | Samples |
| CD54HC368F3A | ACTIVE | CDIP | J | 16 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8681201EA CD54HC368F3A | Samples |
| CD54HCT367F3A | ACTIVE | CDIP | J | 16 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9070601ME A CD54HCT367F3A | Samples |
| CD74HC367E | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HC367E | Samples |
| CD74HC367M | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -55 to 125 | HC367M | |
| CD74HC367M96 | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -55 to 125 | HC367M | Samples |
| CD74HC367MT | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -55 to 125 | HC367M | |
| CD74HC368E | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HC368E | Samples |
| CD74HC368M | ACTIVE | SOIC | D | 16 | 40 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HC368M | Samples |
| CD74HCT367E | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HCT367E | Samples |
| CD74HCT367M | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -55 to 125 | HCT367M | |
| CD74HCT367M96 | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -55 to 125 | HCT367M | Samples |
| CD74HCT367MT | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -55 to 125 | HCT367M | |
| CD74HCT368E | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -55 to 125 | CD74HCT368E | Samples |
| CD74HCT368M | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -55 to 125 | HCT368M | |
| CD74HCT368M96 | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | HCT368M | Samples |
| CD74HCT368MT | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -55 to 125 | HCT368M | |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of ≤ 1000 ppm threshold. Antimony trioxide based flame retardants must also meet the ≤ 1000 ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD54HC367, CD54HC368, CD54HCT367, CD74HC367, CD74HC368, CD74HCT367 :

● Catalog : [CD74HC367](#), [CD74HC368](#), [CD74HCT367](#)

● Military : [CD54HC367](#), [CD54HC368](#), [CD54HCT367](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications